

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wen-Chih CHIOU</td> <td>05/07/2010</td> </tr> <tr> <td>Shau-Lin SHUE</td> <td>05/07/2010</td> </tr> <tr> <td>Weng-Jin WU</td> <td>05/07/2010</td> </tr> <tr> <td>Jui-Pin HUNG</td> <td>05/06/2010</td> </tr> </tbody> </table>		Name	Execution Date	Wen-Chih CHIOU	05/07/2010	Shau-Lin SHUE	05/07/2010	Weng-Jin WU	05/07/2010	Jui-Pin HUNG	05/06/2010
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI, Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300
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CORRESPONDENCE DATA											
<p>Fax Number: (703)518-5499</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036841111</p> <p>Email: sramunto@ipfirm.com</p> <p>Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)</p> <p>Address Line 1: 1700 Diagonal Road, Suite 300</p> <p>Address Line 4: Alexandria, VIRGINIA 22314</p>											
ATTORNEY DOCKET NUMBER:	T5057-K127U										
NAME OF SUBMITTER:	Yoon S. Ham										
<p>Total Attachments: 1</p> <p>source=efiledassgn#page1.tif</p>											

OP \$40.00 12792975

PATENT

501193956

REEL: 024478 FRAME: 0248

Docket No. T5057-K127U

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-------------------|-----------------|
| 1) Wen-Chih CHIOU | 4) Jui-Pin HUNG |
| 2) Shau-Lin SHUE | |
| 3) Weng-Jin WU | |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. **8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SURFACE MODIFICATION FOR HANDLING WAFER THINNING PROCESS

(a) for which an application for United States Letters Patent was filed on 6-3-10, and identified by United States Patent Application No. 12/792,975; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

- | | |
|---|---------------------------|
| 1) <u>Wen-Chih Chioiu</u>
Name: Wen-Chih CHIOU | <u>2010/5/17</u>
Date: |
| 2) <u>Shau-Lin Shue</u>
Name: Shau-Lin SHUE | <u>2010/5/17</u>
Date: |
| 3) <u>Weng-Jin Wu</u>
Name: Weng-Jin WU | <u>2010/5/17</u>
Date: |
| 4) <u>Jui-Pin Hung</u>
Name: Jui-Pin HUNG | <u>2010/5/16</u>
Date: |

PATENT**RECORDED: 06/03/2010****REEL: 024478 FRAME: 0249**